

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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MA2SD310G

Silicon epitaxial planar type

For super high speed switching

■ Features

- $I_{F(AV)} = 200$ mA rectification is possible.
- Low forward voltage: $V_F < 0.47$ V (at $I_F = 200$ mA)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|---|-------------|-------------|------------------|
| Reverse voltage | V_R | 30 | V |
| Repetitive peak reverse voltage | V_{RRM} | 30 | V |
| Forward current (Average) | $I_{F(AV)}$ | 200 | mA |
| Peak forward current | I_{FM} | 300 | mA |
| Non-repetitive peak forward surge current * | I_{FSM} | 1 | A |
| Junction temperature | T_j | 125 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +125 | $^\circ\text{C}$ |

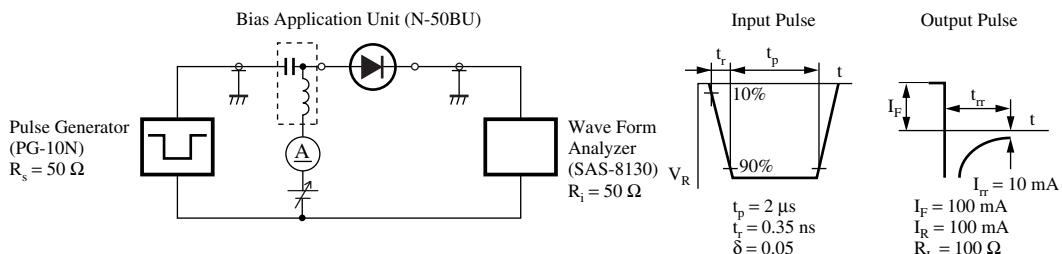
Note) * : The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

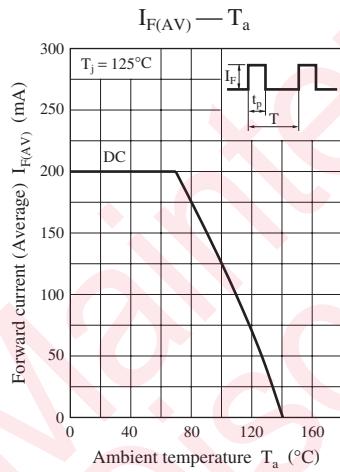
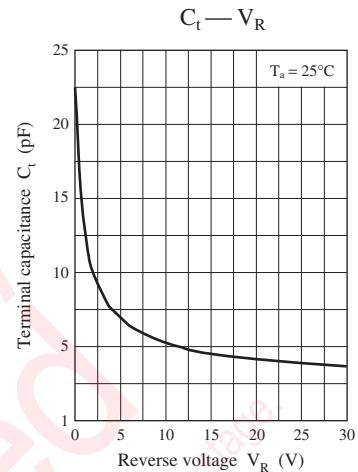
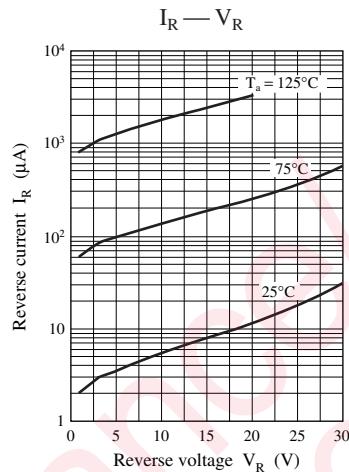
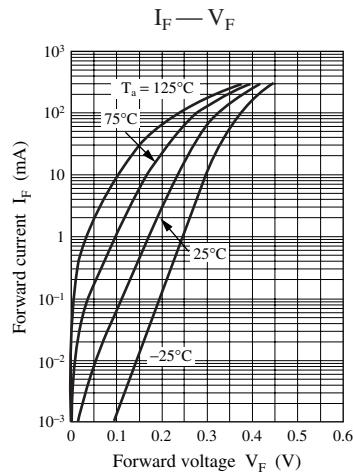
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-------------------------|----------|--|-----|------|------|---------------|
| Forward voltage | V_F | $I_F = 200$ mA | | 0.38 | 0.47 | V |
| Reverse current | I_{R1} | $V_R = 10$ V | | 20 | | μA |
| | I_{R2} | $V_R = 30$ V | | 200 | | |
| Terminal capacitance | C_t | $V_R = 0$ V, $f = 1$ MHz | | 25 | | pF |
| Reverse recovery time * | t_{rr} | $I_F = I_R = 100$ mA $I_{rr} = 10$ mA, $R_L = 100$ Ω | | 2 | | ns |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
4. *: t_{rr} measurement circuit

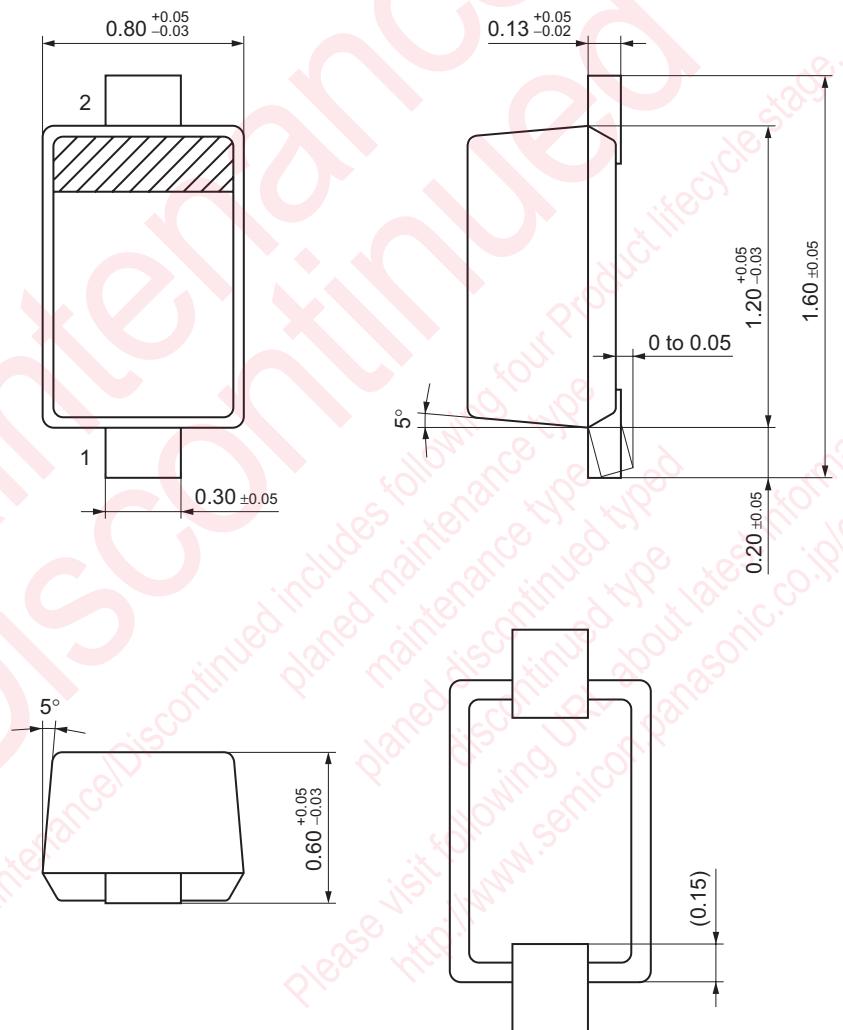




Maintenance/Discontinued includes following four Product lifecycle type
 planned maintenance type
 planned discontinued type
 discontinued type
 Please visit following URL about latest information.
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SSMini2-F4

Unit: mm



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